



Final Product/Process Change Notification

Document #:FPCN21520XG

Issue Date:12 Jul 2023

Title of Change:	Addition of onsemi, Aizu, Japan for wafer fab of NCP730 and NCP711 families for capacity flexibility.
Proposed First Ship date:	18 Oct 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Jan.Gryzbon@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code and custom source.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition
Sites Affected:	
onsemi Sites	External Foundry/Subcon Sites
onsemi Aizu, Japan	None

Description and Purpose:

The onsemi Aizu Wafer Fab located in Aizuwakamatsu, Japan has been qualified to process the ONC25 CMOS process.

The exact same process technology has been transferred as is currently running in the onsemi wafer fab located at Gresham, Oregon, USA. Tool sets are different but the exact same masking layers and steps are being used in the onsemi Aizu.

This is a capacity expansion to supplement the existing onsemi wafer fab. The parts being qualified are dual sourced and may be processed at either wafer fab in the future depending on capacity requirements.

There is no change to the orderable part number. There is no product marking change as a result of this change.

Site / Location	Current:	Proposed:
Wafer Fab:	onsemi Gresham, North America United States Oregon	onsemi Aizu, Asia Japan Fukushima onsemi Gresham, North America United States Oregon

Reliability Data Summary:

QV DEVICE NAME: NCP730ASN330T1G

RMS: S90290, S90289

PACKAGE: TSOP5

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/2400
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	500 cyc	0/240
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
Human Body Model (HBM)	JS001	2kV		pass
Charge Device Model (CDM)	JS002	1kV		Pass
Latch-up (LU)	AEC-Q100-004, JESD78	Class II		pass
Electrical distribution	ON Data Sheet			pass

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCP730BMT1500TBG	NCP730ASN330T1G
NCP730BMT280TBG	NCP730ASN330T1G
NCP711BMT300TBG	NCP730ASN330T1G
NCP711BMT500TBG	NCP730ASN330T1G
NCP730BMT250TBG	NCP730ASN330T1G
NCP711ASN300T1G	NCP730ASN330T1G
NCP711ASNADJT1G	NCP730ASN330T1G
NCP730ASN250T1G	NCP730ASN330T1G
NCP730ASN300T1G	NCP730ASN330T1G
NCP730BMT300TBG	NCP730ASN330T1G
NCP730ASN280T1G	NCP730ASN330T1G
NCP711ASN500T1G	NCP730ASN330T1G
NCP730BMT500TBG	NCP730ASN330T1G



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NCP711BMT330TBG	NCP730ASN330T1G
NCP711ASN330T1G	NCP730ASN330T1G
NCP730BMTADJTBG	NCP730ASN330T1G
NCP730ASN500T1G	NCP730ASN330T1G
NCP730ASNADJT1G	NCP730ASN330T1G
NCP711BMTADJTBG	NCP730ASN330T1G
NCP730BMT330TBG	NCP730ASN330T1G
NCP730ASN330T1G	NCP730ASN330T1G